




Full Material Declaration for attached parts list

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Diotec Semiconductor AG

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Declarations authorised by:

Udo Steinebrunner, Product Manager, -

Declaration effective from: 02 January 2024 [Approved on 23 February 2024, 10:04 GMT]

Materials and substances

Use/Location	Material Group	% w/w of material in the part	Substances in the material	CAS Number	% w/w of substance in the material
Chip (die)	Other inorganic materials	1.5%	Platinum	7440-06-4	2.5%
Encapsulation	Glass	15%	Silver	7440-22-4	8%
			Silicon	7440-21-3	89.5%
			FELLING ZINC OXIDE Exempt from other regulatory requirements	1314-13-2	4%
			Potassium oxide (K2O)	12136-45-7	4.2%
			BORON TRIOXIDE Exempt from other regulatory requirements Exempt from other regulatory requirements	1303-86-2	20%
Leadfinish	Tin plating	23.5%	Silica	7631-86-9	71.8%
Leadframe	Copper alloys	60%	Tin	7440-31-5	100%
			Iron	7439-89-6	2%
			Copper	7440-50-8	98%

Attached parts list

Part number	Part name	Part Mass	Part Mass UoM
DO-213AB/Glass MELF PbF	DO-213AB/Glass MELF PbF	0.12	g